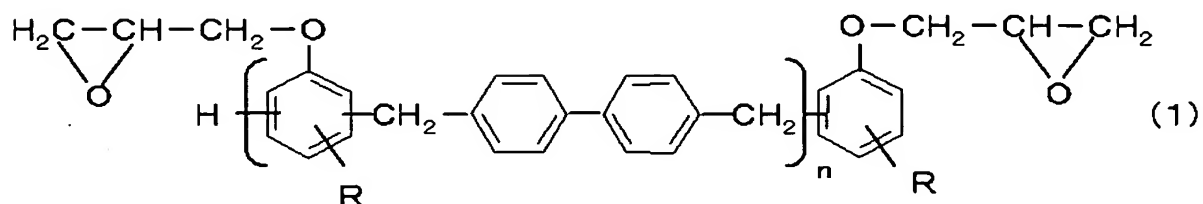


WHAT IS CLAIMED IS:

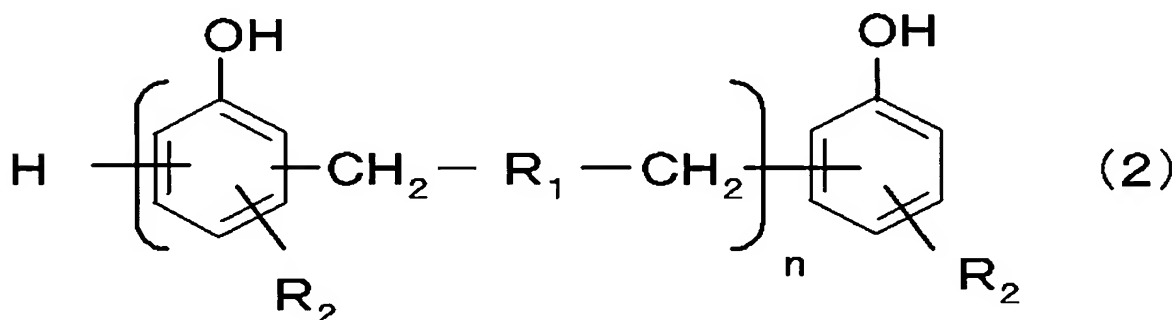
1. A resin composition for encapsulating a semiconductor chip comprising:

5 an epoxy resin (A) represented by general formula (1):



wherein R represents hydrogen or alkyl having up to four carbon atoms; and n is a positive number from 1 to 10 as an average;

a phenol resin (B) represented by general formula (2):



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wherein R₁ represents phenylene or biphenylene; R₂ represents alkyl having up to four carbon atoms; and n is a positive number from 1 to 10 as an average;

an inorganic filler (C);

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a curing accelerator (D);

a silane coupling agent (E); and

Compound (F) containing two and more hydroxyl groups combined with each of adjacent carbon atoms comprising an aromatic ring.

2. The resin composition for encapsulating a semiconductor chip according to Claim 1, wherein the resin composition comprises said Compound (F) in more than or equal to 0.01 wt%.

3. The resin composition for encapsulating a semiconductor
5 chip according to Claim 1, wherein the resin composition comprises said silane coupling agent (E) in 0.01 wt% to 1 wt% both inclusive.

4. The resin composition for encapsulating a semiconductor chip according to Claim 1, wherein said compound (F) contains two hydroxyl groups combined with each of adjacent carbon atoms
10 comprising said aromatic ring.

5. The resin composition for encapsulating a semiconductor chip according to Claim 1, wherein the aromatic ring is a naphthalene ring.

6. The resin composition for encapsulating a semiconductor
15 chip according to Claim 5, wherein said Compound (F) contains two hydroxyl groups combined with each of adjacent carbon atoms comprising said naphthalene ring.

7. The resin composition for encapsulating a semiconductor chip according to Claims 1, wherein the resin composition comprises
20 said inorganic filler (C) in 84 wt% to 90 wt% both inclusive.

8. A semiconductor device wherein a semiconductor chip is encapsulated by the use of a resin composition for encapsulating a semiconductor chip according to Claims 1.